

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

- 1 1. (currently amended): A magnetic head comprising:  
2 a substrate;  
3 a read head being fabricated upon said substrate;  
4 a P1 pole being fabricated upon said read head;  
5 a write gap layer being fabricated upon said P1 pole;  
6 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole  
7 tip includes a first sidewall portion being comprised of a seed layer material and a second  
8 sidewall portion being comprised of ~~electroplated~~ a non-seed layer material, and wherein said P2  
9 pole tip has a thickness dimension t, and a base having a width dimension W;  
10 and wherein said seed layer is comprised of an integrally formed layer of seed layer  
11 material that forms said base of said P2 pole tip and said first sidewall portion of said P2 pole tip  
12 that extends throughout said thickness t of said P2 pole tip.
- 1 2. (currently amended): A magnetic head as described in claim 1 wherein said ~~electroplated~~  
2 non-seed layer material that comprises said second sidewall portion of said P2 pole tip ~~is plated~~  
3 disposed upon said seed layer material that forms said first sidewall portion of said P2 pole tip.
- 1 3. (currently amended): A magnetic head as described in claim 1 wherein said seed layer  
2 material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said  
3 ~~electroplated~~ non-seed layer material is formed with a thickness of approximately 100 Å to  
4 approximately 5000 Å.

1 4. (currently amended): A magnetic head as described in claim 3 wherein said seed layer  
2 material thickness is approximately 250 Å and said ~~electroplated~~ non-seed layer material  
3 thickness is approximately 1500 Å.

1 5. (currently amended): A magnetic head as described in claim 3 wherein said seed layer  
2 material is comprised of deposited NiFe and said ~~electroplated~~ non-seed layer material is  
3 comprised of electroplated NiFe.

1 6. (currently amended): A hard disk drive comprising:  
2 at least one hard disk being fabricated for rotary motion upon a disk drive;  
3 at least one magnetic head adapted to fly over said hard disk for writing data on said hard  
4 disk, said magnetic head including:  
5 a substrate;  
6 a read head being fabricated upon said substrate;  
7 a P1 pole being fabricated upon said read head;  
8 a write gap layer being fabricated upon said P1 pole;  
9 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole  
10 tip includes a first sidewall portion being comprised of a seed layer and a second sidewall portion  
11 being comprised of ~~electroplated~~ a non-seed layer material, and wherein said P2 pole tip has a  
12 thickness dimension t, and a base having a width dimension W;

13 and wherein said seed layer is comprised of an integrally formed layer of seed layer  
14 material that forms said base of said P2 pole tip and said first sidewall portion of said P2 pole tip  
15 that extends throughout said thickness t of said P2 pole tip.

1 7. (currently amended): A hard disk drive as described in claim 6 wherein said ~~electroplated~~  
2 non-seed layer material that comprises said second sidewall portion of said P2 pole tip ~~is plated~~  
3 disposed upon said seed layer material that forms said first sidewall portion of said P2 pole tip.

1 8. (currently amended): A hard disk drive as described in claim 6 wherein said seed layer  
2 material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said  
3 ~~electroplated~~ non-seed layer material is formed with a thickness of approximately 100 Å to  
4 approximately 5000 Å.

1 9. (currently amended): A hard disk drive as described in claim 8 wherein said seed layer  
2 material thickness is approximately 250 Å and said ~~electroplated~~ non-seed layer material  
3 thickness is approximately 1500 Å.

1 10. (currently amended): A hard disk drive as described in claim 8 wherein said seed layer  
2 material is comprised of deposited NiFe and said ~~electroplated~~ non-seed layer material is  
3 comprised of electroplated NiFe.

11-18 (withdrawn)

1 19. (currently amended): A magnetic head comprising:  
2 a substrate;  
3 a read head being fabricated upon said substrate;  
4 a P1 pole being fabricated upon said read head;  
5 a write gap layer being fabricated upon said P1 pole;  
6 a P2 pole tip being fabricated upon portions of said write gap layer, wherein said P2 pole  
7 tip includes a base surface layer that is disposed upon said write gap layer and a first sidewall  
8 surface layer that is disposed generally perpendicularly to said base surface layer, and wherein  
9 said base surface layer and said first sidewall surface layer are comprised of an integrally formed  
10 layer of P2 pole tip seed layer material;  
11 and wherein said P2 pole tip includes ~~an electroplated~~ a non-seed layer material portion,  
12 and wherein said P2 pole tip includes a second sidewall surface layer that is disposed opposite to  
13 said first sidewall surface layer, and wherein said second sidewall surface layer is comprised of  
14 said ~~electroplated~~ non-seed layer material.

1 20. (currently amended): A magnetic head as described in claim 19 wherein said base  
2 surface layer defines a width W of said P2 pole tip and said first sidewall layer defines a  
3 thickness t of said P2 pole tip.

1 21. (currently amended): A magnetic head as described in claim 20, wherein said  
2 ~~electroplated non-seed layer~~ material portion is ~~plated~~ disposed in part upon said first sidewall  
3 surface seed layer material.

1 22. (currently amended): A magnetic head as described in claim 21 wherein said seed layer  
2 material is formed with a thickness of approximately 50 Å to approximately 500 Å, and said  
3 ~~electroplated~~ non-seed layer material is formed with a thickness of approximately 100 Å to  
4 approximately 5000 Å.

1 23. (currently amended): A magnetic head as described in claim 21 wherein said seed layer  
2 material thickness is approximately 250 Å and said ~~electroplated~~ non-seed layer material  
3 thickness is approximately 1500 Å.

1 24. (currently amended): A magnetic head as described in claim 21 wherein said seed layer  
2 material is comprised of deposited NiFe and said ~~electroplated~~ non-seed layer material is  
3 comprised of electroplated NiFe.